

## 103358786

Please record the attached original document or copy thereof.

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1 Name of mantry on nanting conviouing on	- I		
1. Name of party or parties conveying an	2. Name and address of party or parties		
interest:	receiving an interest:		
	Name: Hynix Semiconductor Inc.		
Eun Soo KIM	Street Address: San 136-1, Ami-ri, Bubal-		
Seung Hee HONG	eub, Icheon-si		
Cheol Mo JEONG	City: Kyoungki-do		
Jung Geun KIM	Country: Republic of Korea		
3. Description of the interest conveyed:			
X Assignment	Other: 01/03/2007 HDESTAL 00000009 11647087		
Merger	84 FC:882) ( 48.08 OF		
Change of Name			
Security Agreement			
Execution Date: December 21, 2006	C		
4. Application number(s) or patent	If the document is being filed together with		
number(s). Additional sheet attached?	a new application, the execution date of the		
YES NO_X	application is: December 27, 2006		
A. Patent application no.:	B. Patent no.(s):		
5. Name and address of party to whom	6. Number of applications and/or patents		
correspondence concerning this cover sheet	identified on this cover sheet: 1		
should be mailed:	7. Amount of fee enclosed or authorized to		
Name: James P. Zeller	be charged:		
Reg. No. 28,491	\$ 40.00		
MARSHALL, GERSTEIN & BORUN LLP			
Street Address: 6300 Sears Tower,	8. Any additional required fee may be		
233 South Wacker Drive	charged, or any overpayment credited to		
City: Chicago	our deposit account: 13-2855		
State: Illinois Zip: 60606-6357			

9. To the best of my knowledge and belief, the information contained on this cover sheet is true and correct and any copy submitted is a true copy of the original document.

Date: December 27, 2006

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Total number of pages including cover sheet, attachments, and document: 3

## ASSIGNMENT

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Filed:

Title: METHOD OF FORMING METAL LINE OF SEMICONDUCTOR MEMORY DEVICE

For \$10.00 (Ten Dollars) and other good and sufficient consideration, the receipt and sufficiency whereof are hereby acknowledged, the undersigned hereby assign to <a href="Hynix Semiconductor Inc.">Hynix Semiconductor Inc.</a>, of San 136-1, <a href="Ami-ri">Ami-ri</a>, Bubal-eub, Icheon-si</a>, Kyoungki-do, Republic of Korea, (hereinafter "Assignee"), its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for Letters Patent of the United States, executed by the undersigned on, \_\_\_\_\_\_ and in said application and any and all other applications, both United States and foreign, which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States and foreign countries, which may be obtained on any of said applications, and in any reissue or extension thereof.

The undersigned hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to said assignee.

The undersigned hereby authorize and request the attorneys of record in said application to insert in this assignment the execution date and/or filing date and serial number of said application when officially known.

The undersigned warrant themselves to be the owners of the interest herein assigned and to have the right to make this assignment and further warrant that there are no outstanding prior assignments, licenses, or other rights in the interest herein assigned.

For said consideration the undersigned hereby agree, upon the request and at the expense of said assignee, its successors and assigns, to execute any and all divisional, continuation, continuation-in-part and substitute applications for said invention or improvements, and any necessary oath or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon said application, and any and all applications and other documents for Letters Patent in foreign countries on said invention or improvements, that said assignee, its successors or assigns, may deem necessary or expedient, and for the aforesaid consideration the undersigned further agree upon the request of said assignee, its successors or assigns, in the event of any application or Letters Patent assigned herein becoming involved in Interference, to cooperate to the best of the ability of the undersigned with said assignee, its successors or assigns, in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof, the undersigned hereby agreeing to perform, upon request, any and all affirmative acts to obtain said Letters Patent, both United States and foreign, and vest all rights therein hereby conveyed in said assignee, its successors and assigns, whereby said Letters Patent will be held and enjoyed by said assignee, its successors and assigns, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

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Date:	pelember 21. 2006	Signature:	Name: EUN SOO KIM
Date:	pelember 21. 2006	Signature:	Seung Hee Hory Name: Seung Hee HONG
Date:	pecember 21, 2006	Signature:	Name: Cheol Mo Jeong  Name: Cheol Mo JEONG
Date:	December 21. 2006	Signature:	Jung Geun Fim Name: Jung Geun KIM
Date:		Signature:	Name:
Date:		Signature:	Name:
Date:		Signature:	

Name:

**RECORDED: 12/27/2006**